

Product Change Notification

(Notification – P2203015-DI)

(IMO-AZ-22-0002-1 / IMO-AZ-22-0004-1 / IMO-AB-22-0016-1 /
IMO-AB-22-0020-1 / IMO-AB-22-0014-1 / IMO-AB-22-0022-1)

March 31, 2022

To: *Our Valued Customer (Insert Customer Name Here)*

The purpose of this notification is to communicate a product change of select Renesas Electronics America, Inc. (REA) devices.

This notification announces one or more of the following assembly changes for select M16C and M32C devices.

1. Bonding Wire Change from Au to Cu
2. Lead Frame Change
3. Additional Mold Compound
4. Solder Paste Change from SnCu to Sn
5. Top Mark Change
6. Assembly Site Reduction from RSB & ATJ to RSB only

The “Change Notes” in the part list outlines the specific change(s).

Some devices have new part numbers, other devices will have no change to the part number. There is no impact to form, fit, quality & reliability of the products.

Affected Products: A review of our records indicates the list of products in the appendix may affect your company.

Part numbers given in this list are for active part numbers in REA database at the time of this notification.

Key Dates:

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| Shipments from REA of the parts with the assembly material changes begins. |
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|------------------|
| November 1, 2022 |
|------------------|

Response: No response is required. REA will consider this notification approved 30 days after its issue. If you anticipate volumes beyond your regular rate prior to the transition date, please contact your REA sales representative with a forecast of your requirements.

If the customer provides a timely acknowledgement, the customer shall have 90 days (an additional 60 days) from the date of receipt of this notification in which to make any objections to the notification. If the customer does not make any objections to this notification within 90 days of the receipt of the notification, then Renesas will consider the notification as approved. If customer cannot accept the notification, then the customer must provide Renesas with a last time buy demand and purchase order.

Please contact your REA sales representative for any questions or comments. Thank you for your attention.

Sincerely,

Renesas Electronics America, Inc.

Appendix A: Affected Part Numbers

| Booking Part Number | Replacement PN | Change Notes |
|---------------------|--------------------|---|
| M30260F3AGP#U3A | M30260F3AGP#33A | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 1); |
| M30260F3AGP#U5A | M30260F3AGP#35A | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 1); |
| M30260F3AGP#U7A | M30260F3AGP#37A | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 1); |
| M30260F6AGP#U3A | M30260F6AGP#33A | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 1); |
| M30260F6AGP#U5A | M30260F6AGP#35A | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 1); |
| M30260F6AGP#U7A | M30260F6AGP#37A | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 1); |
| M30260F6AGP#W9A | M30260F6AGP#59A | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 6); |
| M30260F6BGP#U9A | M30260F6BGP#39A | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 1); |
| M30260F8AGP#U3A | M30260F8AGP#33A | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 1); |
| M30260F8AGP#U5A | M30260F8AGP#35A | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 1); |
| M30260F8AGP#U7A | M30260F8AGP#37A | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 1); |
| M30260F8AGP#U9A | M30260F8AGP#39A | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 1); |
| M30260F8BGP#U3A | M30260F8BGP#33A | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 1); |
| M30260M6A-XXXGP#U5 | M30260M6A-XXXGP#35 | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 1); |
| M30280F6HP#U5B | M30280F6HP#35B | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 2); |
| M30280F6HP#U9B | M30280F6HP#39B | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 2); |
| M30280F8HP#U3B | M30280F8HP#33B | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 2); |
| M30280F8HP#U5B | M30280F8HP#35B | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 2); |
| M30280FAHP#U3B | M30280FAHP#33B | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 2); |
| M30280FAHP#U5B | M30280FAHP#35B | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 2); |
| M30280FAHP#U7B | M30280FAHP#37B | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 2); |
| M30280FAHP#U9B | M30280FAHP#39B | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 2); |
| M30280FCHP#U3B | M30280FCHP#33B | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 2); |
| M30280FCHP#U5B | M30280FCHP#35B | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 2); |
| M30280FCHP#U7B | M30280FCHP#37B | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 2); |
| M30280FCHP#U9B | M30280FCHP#39B | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 2); |
| M30290FAHP#U3A | M30290FAHP#33A | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 2); |
| M30290FAHP#U5A | M30290FAHP#35A | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 2); |
| M30290FCHP#U3A | M30290FCHP#33A | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 2); |
| M30290FCHP#U5A | M30290FCHP#35A | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 2); |
| M30290FCHP#U7A | M30290FCHP#37A | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 2); |
| M30290FCHP#U9A | M30290FCHP#39A | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 2); |
| M30302FAPGP#U3 | M30302FAPGP#33 | Additional Mold Compound; Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 3); Assembly Site Reduction (RSB & ATJ to RRSB Only |
| M30302FAPGP#U5 | M30302FAPGP#35 | Additional Mold Compound; Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 3); Assembly Site Reduction (RSB & ATJ to RRSB Only |
| M30302FCPGP#U3 | M30302FCPGP#33 | Additional Mold Compound; Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 3); Assembly Site Reduction (RSB & ATJ to RRSB Only |
| M30302FCPGP#U5 | M30302FCPGP#35 | Additional Mold Compound; Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 3); Assembly Site Reduction (RSB & ATJ to RRSB Only |

Appendix A: Affected Part Numbers (cont.)

| Booking Part Number | Replacement PN | Change Notes |
|---------------------|--------------------|--|
| M30302FEPGP#U3 | M30302FEPGP#33 | Additional Mold Compound; Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 3); Assembly Site Reduction (RSB & ATJ to RRSB Only) |
| M30302FEPGP#U5 | M30302FEPGP#35 | Additional Mold Compound; Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 3); Assembly Site Reduction (RSB & ATJ to RRSB Only) |
| M30302GAPGP#U5 | M30302GAPGP#35 | Lead Frame Change (Frame B to Frame C); Additional Mold Compound; Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 3); Assembly Site Reduction (RSB & ATJ to RRSB Only) |
| M30302SPGP#U5 | M30302SPGP#35 | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 3); |
| M3030RFAPGP#U5 | M3030RFAPGP#35 | Lead Frame Change (Frame B to Frame C); Additional Mold Compound; Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 3); Assembly Site Reduction (RSB & ATJ to RRSB Only) |
| M3030RFCPGP#U5 | M3030RFCPGP#35 | Lead Frame Change (Frame B to Frame C); Additional Mold Compound; Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 3); Assembly Site Reduction (RSB & ATJ to RRSB Only) |
| M3030RFGPGP#U3 | M3030RFGPGP#33 | Lead Frame Change (Frame B to Frame C); Additional Mold Compound; Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 3); Assembly Site Reduction (RSB & ATJ to RRSB Only) |
| M3030RFGPGP#U5 | M3030RFGPGP#35 | Lead Frame Change (Frame B to Frame C); Additional Mold Compound; Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 3); Assembly Site Reduction (RSB & ATJ to RRSB Only) |
| M30620FCPGP#U3C | M30620FCPGP#33C | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 3); |
| M30620FCPGP#U5C | M30620FCPGP#35C | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 3); |
| M30620FCPGP#U9C | M30620FCPGP#39C | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 3); |
| M30620MCP-095GP#U3 | M30620MCP-095GP#33 | Lead Frame Change (Frame B to Frame C); Solder Paste Change (SnCu to Sn); |
| M30620MCP-599GP#U0 | M30620MCP-599GP#30 | Lead Frame Change (Frame B to Frame C); Solder Paste Change (SnCu to Sn); |
| M30620MCP-D01GP#U3 | M30620MCP-D01GP#33 | Lead Frame Change (Frame B to Frame C); Solder Paste Change (SnCu to Sn); |
| M30620SPGP#U3C | M30620SPGP#33C | Lead Frame Change (Frame B to Frame C); Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 3); |
| M30620SPGP#U5C | M30620SPGP#35C | Lead Frame Change (Frame B to Frame C); Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 3); |
| M30622F8PGP#U3C | M30622F8PGP#33C | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 3); |
| M30622F8PGP#U5C | M30622F8PGP#35C | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 3); |
| M30622M6P-XXXGP#U0 | M30622M6P-XXXGP#30 | Lead Frame Change (Frame B to Frame C); Solder Paste Change (SnCu to Sn); |
| M30622M6P-XXXGP#U3 | M30622M6P-XXXGP#33 | Lead Frame Change (Frame B to Frame C); Solder Paste Change (SnCu to Sn); |
| M30622M8P-XXXGP#U0 | M30622M8P-XXXGP#30 | Lead Frame Change (Frame B to Frame C); Solder Paste Change (SnCu to Sn); |
| M30622MEP-D27GP#U3 | M30622MEP-D27GP#33 | Solder Paste Change (SnCu to Sn); |
| M30622SPGP#U5C | M30622SPGP#35C | Lead Frame Change (Frame B to Frame C); Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 3); |
| M30624FGPGP#U3C | M30624FGPGP#33C | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 3); |
| M30624FGPGP#U5C | M30624FGPGP#35C | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 3); |
| M30624FGPGP#U7C | M30624FGPGP#37C | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 3); |
| M30624FGPGP#U9C | M30624FGPGP#39C | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 3); |
| M30624MGP-XXXGP#U3 | M30624MGP-XXXGP#33 | Solder Paste Change (SnCu to Sn); |
| M30626FHPGP#U9C | M30626FHPGP#39C | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 3); |
| M30626FHPGP#UJC | M30626FHPGP#3JC | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 7); |
| M30626FJPGP#U3C | M30626FJPGP#33C | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 3); |
| M30626FJPGP#U5C | M30626FJPGP#35C | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 3); |
| M30626FJPGP#U7C | M30626FJPGP#37C | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 3); |

Appendix A: Affected Part Numbers (cont.)

| Booking Part Number | Replacement PN | Change Notes |
|---------------------|------------------|--|
| M3062LFGPGP#U3C | M3062LFGPGP#33C | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 3); |
| M3062LFGPGP#U5C | M3062LFGPGP#35C | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 3); |
| M3062LFGPGP#U7C | M3062LFGPGP#37C | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 3); |
| M3062LFGPGP#U9C | M3062LFGPGP#39C | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 3); |
| M30800SAGP-BL#U5 | M30800SAGP-BL#35 | Solder Paste Change (SnCu to Sn); |
| M30840SGP#U5 | M30840SGP#35 | Solder Paste Change (SnCu to Sn); |
| M30843FHGP#U5 | M30843FHGP#35 | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 5); |
| M30843FJGP#U5 | M30843FJGP#35 | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 5); |
| M30843FWGP#U5 | M30843FWGP#35 | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 5); |
| M30853FHGP#U5 | M30853FHGP#35 | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 5); |
| M30853FJGP#U5 | M30853FJGP#35 | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 5); |
| M30873FHAGP#U5 | M30873FHAGP#35 | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 5); |
| M30873FHBGP#U5 | M30873FHBGP#35 | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 5); |
| M30873FHGP#U5 | M30873FHGP#35 | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 5); |
| M30876FJAGP#U5 | M30876FJAGP#35 | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 5); |
| M30876FJBGP#U5 | M30876FJBGP#35 | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 5); |
| M30879FKBGP#U5 | M30879FKBGP#35 | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 5); |
| M30879FLAGP#U5 | M30879FLAGP#35 | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 5); |
| M30879FLBGP#U5 | M30879FLBGP#35 | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 5); |
| M30879FLGP#U5 | M30879FLGP#35 | Solder Paste Change (SnCu to Sn); Top Mark Change (Figure 5); |
| M308A0SGP#U5 | M308A0SGP#35 | Additional Mold Compound; Solder Paste Change (SnCu to Sn); |
| R5F363AKDFB#U0 | R5F363AKDFB#30 | Bond Wire Material Change (Au to Cu); Lead Frame Change (Frame A to Frame C); Additional Mold Compound; Solder Paste Change (SnCu to Sn); Assembly Site Reduction (RSB & ATJ to RRSB Only) |
| R5F363AKNFB#30 | No PN Change | Lead Frame Change (Frame A to Frame C); Additional Mold Compound; |
| R5F363AMDFB#30 | No PN Change | Lead Frame Change (Frame A to Frame C); Additional Mold Compound; |
| R5F363AMDFB#U0 | R5F363AMDFB#30 | Bond Wire Material Change (Au to Cu); Lead Frame Change (Frame A to Frame C); Additional Mold Compound; Solder Paste Change (SnCu to Sn); Assembly Site Reduction (RSB & ATJ to RRSB Only) |
| R5F363AMNFB#30 | No PN Change | Lead Frame Change (Frame A to Frame C); Additional Mold Compound; |
| R5F3640DDFB#30 | No PN Change | Additional Mold Compound; |
| R5F3640DDFB#U0 | R5F3640DDFB#30 | Bond Wire Material Change (Au to Cu); Additional Mold Compound; Solder Paste Change (SnCu to Sn); Assembly Site Reduction (RSB & ATJ to RRSB Only) |
| R5F3640DNFB#30 | No PN Change | Additional Mold Compound; |
| R5F3640MCNFB#30 | No PN Change | Lead Frame Change (Frame A to Frame C); Additional Mold Compound; |
| R5F3640MDFB#U0 | R5F3640MDFB#30 | Bond Wire Material Change (Au to Cu); Lead Frame Change (Frame B to Frame C); Additional Mold Compound; Solder Paste Change (SnCu to Sn); Assembly Site Reduction (RSB & ATJ to RRSB Only) |
| R5F3640MNFB#U0 | R5F3640MNFB#30 | Bond Wire Material Change (Au to Cu); Lead Frame Change (Frame B to Frame C); Additional Mold Compound; Solder Paste Change (SnCu to Sn); Assembly Site Reduction (RSB & ATJ to RRSB Only) |
| R5F364A6DFB#U0 | R5F364A6DFB#30 | Bond Wire Material Change (Au to Cu); Lead Frame Change (Frame A to Frame C); Additional Mold Compound; Solder Paste Change (SnCu to Sn); Assembly Site Reduction (RSB & ATJ to RRSB Only) |
| R5F364A6NFB#30 | No PN Change | Lead Frame Change (Frame A to Frame C); Additional Mold Compound; |
| R5F364A6NFB#U0 | R5F364A6NFB#30 | Bond Wire Material Change (Au to Cu); Lead Frame Change (Frame A to Frame C); Additional Mold Compound; Solder Paste Change (SnCu to Sn); Assembly Site Reduction (RSB & ATJ to RRSB Only) |
| R5F364AEDFB#30 | No PN Change | Lead Frame Change (Frame A to Frame C); Additional Mold Compound; |

Appendix A: Affected Part Numbers (cont.)

| Booking Part Number | Replacement PN | Change Notes |
|---------------------|----------------|--|
| R5F364AEDFB#U0 | R5F364AEDFB#30 | Bond Wire Material Change (Au to Cu); Lead Frame Change (Frame A to Frame C); Additional Mold Compound; Solder Paste Change (SnCu to Sn); Assembly Site Reduction (RSB & ATJ to RRSB Only) |
| R5F364AENFB#30 | No PN Change | Lead Frame Change (Frame A to Frame C); Additional Mold Compound; |
| R5F364AENFB#U0 | R5F364AENFB#30 | Bond Wire Material Change (Au to Cu); Lead Frame Change (Frame A to Frame C); Additional Mold Compound; Solder Paste Change (SnCu to Sn); Assembly Site Reduction (RSB & ATJ to RRSB Only) |
| R5F364AENFB#V2 | R5F364AENFB#30 | Bond Wire Material Change (Au to Cu); Lead Frame Change (Frame A to Frame C); Additional Mold Compound; |
| R5F364AKNFB#30 | No PN Change | Lead Frame Change (Frame A to Frame C); Additional Mold Compound; |
| R5F364AMDFB#30 | No PN Change | Lead Frame Change (Frame A to Frame C); Additional Mold Compound; |
| R5F364AMDFB#U0 | R5F364AMDFB#30 | Bond Wire Material Change (Au to Cu); Lead Frame Change (Frame A to Frame C); Additional Mold Compound; Solder Paste Change (SnCu to Sn); Assembly Site Reduction (RSB & ATJ to RRSB Only) |
| R5F364AMNFB#30 | No PN Change | Lead Frame Change (Frame A to Frame C); Additional Mold Compound; |
| R5F364AMNFB#U0 | R5F364AMNFB#30 | Bond Wire Material Change (Au to Cu); Lead Frame Change (Frame A to Frame C); Additional Mold Compound; Solder Paste Change (SnCu to Sn); Assembly Site Reduction (RSB & ATJ to RRSB Only) |
| R5F36506DFB#30 | No PN Change | Lead Frame Change (Frame A to Frame C); Additional Mold Compound; |
| R5F36506DFB#U0 | R5F36506DFB#30 | Bond Wire Material Change (Au to Cu); Lead Frame Change (Frame A to Frame C); Additional Mold Compound; Solder Paste Change (SnCu to Sn); Assembly Site Reduction (RSB & ATJ to RRSB Only) |
| R5F36506NFB#30 | No PN Change | Lead Frame Change (Frame A to Frame C); Additional Mold Compound; |
| R5F3650EDFB#30 | No PN Change | Lead Frame Change (Frame A to Frame C); Additional Mold Compound; |
| R5F3650EDFB#U0 | R5F3650EDFB#30 | Bond Wire Material Change (Au to Cu); Lead Frame Change (Frame A to Frame C); Additional Mold Compound; Solder Paste Change (SnCu to Sn); Assembly Site Reduction (RSB & ATJ to RRSB Only) |
| R5F3650ENFB#30 | No PN Change | Lead Frame Change (Frame A to Frame C); Additional Mold Compound; |
| R5F3650KDFB#30 | No PN Change | Lead Frame Change (Frame A to Frame C); Additional Mold Compound; |
| R5F3650KDFB#30 | No PN Change | Lead Frame Change (Frame A to Frame C); Additional Mold Compound; |
| R5F3650KDFB#U0 | R5F3650KDFB#30 | Bond Wire Material Change (Au to Cu); Lead Frame Change (Frame A to Frame C); Additional Mold Compound; Solder Paste Change (SnCu to Sn); Assembly Site Reduction (RSB & ATJ to RRSB Only) |
| R5F3650KDFB#UA | R5F3650KDFB#3A | Bond Wire Material Change (Au to Cu); Lead Frame Change (Frame A to Frame C); Additional Mold Compound; Solder Paste Change (SnCu to Sn); Assembly Site Reduction (RSB & ATJ to RRSB Only) |
| R5F3650KNFB#30 | No PN Change | Lead Frame Change (Frame A to Frame C); Additional Mold Compound; |
| R5F3650KNFB#U0 | R5F3650KNFB#30 | Bond Wire Material Change (Au to Cu); Lead Frame Change (Frame A to Frame C); Additional Mold Compound; Solder Paste Change (SnCu to Sn); Assembly Site Reduction (RSB & ATJ to RRSB Only) |
| R5F3650MCDFB#30 | No PN Change | Lead Frame Change (Frame A to Frame C); Additional Mold Compound; |
| R5F3650MDFB#30 | No PN Change | Lead Frame Change (Frame A to Frame C); Additional Mold Compound; |
| R5F3650MNFB#30 | No PN Change | Lead Frame Change (Frame A to Frame C); Additional Mold Compound; |
| R5F3650NCNFB#30 | No PN Change | Lead Frame Change (Frame A to Frame C); Additional Mold Compound; |
| R5F3650NDFB#30 | No PN Change | Lead Frame Change (Frame A to Frame C); Additional Mold Compound; |
| R5F3650NDFB#U0 | R5F3650NDFB#30 | Bond Wire Material Change (Au to Cu); Lead Frame Change (Frame A to Frame C); Additional Mold Compound; Solder Paste Change (SnCu to Sn); Assembly Site Reduction (RSB & ATJ to RRSB Only) |

Appendix A: Affected Part Numbers (cont.)

| Booking Part Number | Replacement PN | Change Notes |
|---------------------|----------------|--|
| R5F3650NNFB#30 | No PN Change | Lead Frame Change (Frame A to Frame C); Additional Mold Compound; |
| R5F3650NNFB#U0 | R5F3650NNFB#30 | Bond Wire Material Change (Au to Cu); Lead Frame Change (Frame A to Frame C); Additional Mold Compound; Solder Paste Change (SnCu to Sn); Assembly Site Reduction (RSB & ATJ to RRSB Only) |
| R5F3650RDFB#30 | No PN Change | Additional Mold Compound; |
| R5F3650RNFB#U0 | R5F3650RNFB#30 | Bond Wire Material Change (Au to Cu); Additional Mold Compound; Solder Paste Change (SnCu to Sn); Assembly Site Reduction (RSB & ATJ to RRSB Only) |
| R5F3650TDFB#30 | No PN Change | Additional Mold Compound; |
| R5F3650TDFB#U0 | R5F3650TDFB#30 | Bond Wire Material Change (Au to Cu); Additional Mold Compound; Solder Paste Change (SnCu to Sn); Assembly Site Reduction (RSB & ATJ to RRSB Only) |
| R5F3650TNFB#30 | No PN Change | Additional Mold Compound; |
| R5F36CA6DFB#30 | No PN Change | Lead Frame Change (Frame B to Frame C); Additional Mold Compound; |
| R5F36CA6NFB#U0 | R5F36CA6NFB#30 | Bond Wire Material Change (Au to Cu); Lead Frame Change (Frame B to Frame C); Additional Mold Compound; Solder Paste Change (SnCu to Sn); Assembly Site Reduction (RSB & ATJ to RRSB Only) |
| R5F36CAENFB#30 | No PN Change | Lead Frame Change (Frame B to Frame C); Additional Mold Compound; |
| R5F36CAKNFB#U0 | R5F36CAKNFB#30 | Bond Wire Material Change (Au to Cu); Lead Frame Change (Frame B to Frame C); Additional Mold Compound; Solder Paste Change (SnCu to Sn); Assembly Site Reduction (RSB & ATJ to RRSB Only) |
| R5F36CAMDFB#30 | No PN Change | Lead Frame Change (Frame B to Frame C); Additional Mold Compound; |
| R5F36CAMDFB#U0 | R5F36CAMDFB#30 | Bond Wire Material Change (Au to Cu); Lead Frame Change (Frame B to Frame C); Additional Mold Compound; Solder Paste Change (SnCu to Sn); Assembly Site Reduction (RSB & ATJ to RRSB Only) |
| R5F36CAMNFB#30 | No PN Change | Lead Frame Change (Frame B to Frame C); Additional Mold Compound; |
| R5F36CAMNFB#U0 | R5F36CAMNFB#30 | Bond Wire Material Change (Au to Cu); Lead Frame Change (Frame B to Frame C); Additional Mold Compound; Solder Paste Change (SnCu to Sn); Assembly Site Reduction (RSB & ATJ to RRSB Only) |

Appendix B: Change Summary

| Item | Current | After Change |
|------------------|--|------------------------------|
| Bonding Wire | Cu | Cu Only |
| | Cu or Au | |
| | Au | |
| Lead Frame | Frame A | Frame C |
| | Frame B | |
| | Frame D | Frame E |
| Mold Compound | Compound A | Compound A or B |
| | Compound B | Compound B |
| Solder Paste | Sn | Sn Only |
| | SnCu | |
| Top Mark | - | Changed for Specific Devices |
| Assembly Factory | RSB: Renesas Semiconductor (Beijing) Co., Ltd. | RSB Only |
| | RSB: Renesas Semiconductor (Beijing) Co., Ltd ATJ: Amkor Technology Japan, Inc. | |

Appendix C: Top Mark Change Diagrams

Figure1

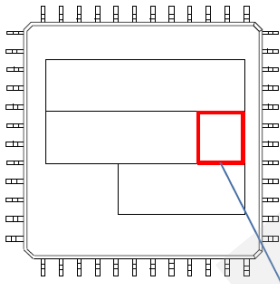
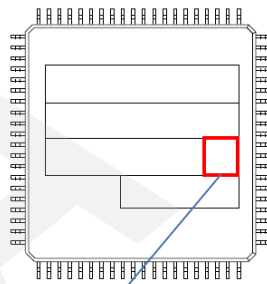


Figure2



The "Product Code" (2 characters) printed here will be changed.

Figure3

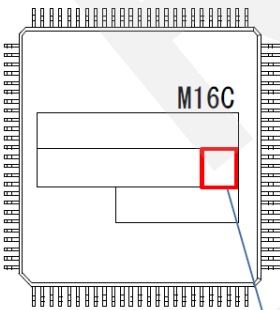
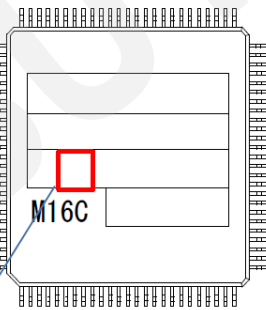
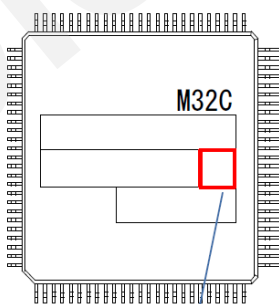


Figure4



The "Product Code" (2 characters) printed here will be changed.

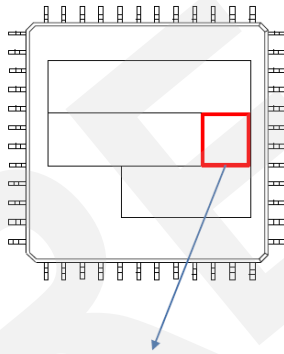
Figure5



The "Product Code" (2 characters) printed here will be changed.

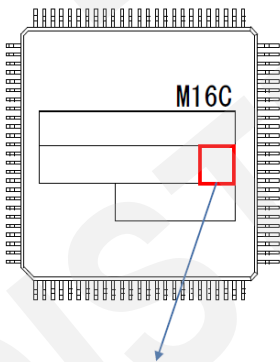
Appendix C: Top Mark Change Diagrams (cont.)

Figure6



The "Product Code" (2 characters) printed here will be changed.

Figure7



The "Product Code" (2 characters) printed here will be changed.